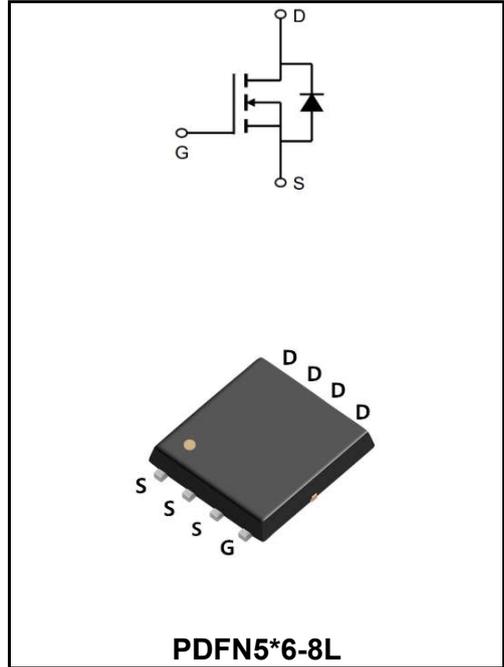


**30V N-CHANNEL ENHANCEMENT MODE MOSFET**

**MAIN CHARACTERISTICS**

<b>I<sub>D</sub></b>	80A
<b>V<sub>DSS</sub></b>	30V
<b>R<sub>DS(on)-typ(@V<sub>GS</sub>=10V)</sub></b>	< 4.0mΩ (Type:2.9mΩ)



**Application**

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW80N03NF	PDFN5*6-8L	YFW 80N03NF XXXXX	5000PCS/Tape

**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage	<b>V<sub>DS</sub></b>	30	<b>V</b>
Gate - Source Voltage	<b>V<sub>GS</sub></b>	±20	<b>V</b>
Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1.6</sup> @T <sub>c</sub> =25°C	<b>I<sub>D</sub></b>	80	<b>A</b>
Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1.6</sup> @T <sub>c</sub> =100°C	<b>I<sub>D</sub></b>	65	<b>A</b>
Pulsed Drain Current <sup>note1</sup>	<b>I<sub>DM</sub></b>	400	<b>A</b>
Single Pulsed Avalanche Energy <sup>note2</sup>	<b>E<sub>AS</sub></b>	320	<b>mJ</b>
Avalanche Current	<b>I<sub>AS</sub></b>	45.8	<b>A</b>
Storage Temperature Range	<b>T<sub>STG</sub></b>	-55 to +175	<b>°C</b>
Operating Junction Temperature Range	<b>T<sub>J</sub></b>	-55 to +175	<b>°C</b>
Total Power Dissipation <sup>4</sup> @T <sub>c</sub> =25°C	<b>P<sub>D</sub></b>	88	<b>W</b>
Total Power Dissipation <sup>4</sup> @T <sub>A</sub> =25°C	<b>P<sub>D</sub></b>	44	<b>W</b>
Thermal Resistance Junction-ambient <sup>1</sup>	<b>R<sub>θJA</sub></b>	58	<b>°C/W</b>
Thermal Resistance Junction-Ambient 1 (t ≤10s)	<b>R<sub>θJA</sub></b>	20	<b>°C/W</b>
Thermal Resistance, Junction to Case <sup>1</sup>	<b>R<sub>θJC</sub></b>	2.3	<b>°C/W</b>

**Maximum Ratings at Tc=25°C unless otherwise specified**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	<b>V(BR)DSS</b>	30	-	-	<b>V</b>
Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V$	<b>I<sub>DSS</sub></b>	-	-	1.0	<b>μA</b>
Gate to Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	<b>I<sub>GSS</sub></b>	-	-	±100	<b>nA</b>
Gate -Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	<b>V<sub>GS(th)</sub></b>	1.0	1.5	2.5	<b>V</b>
Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=24A$	<b>R<sub>DS(on)</sub></b>	-	2.9	4.0	<b>mΩ</b>
	$V_{GS}=4.5V, I_D=12A$		-	5.3	6.5	
Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	<b>R<sub>g</sub></b>	-	-	3.3	<b>Ω</b>
Forward Transconductance	$V_{DS}=10V, I_D=10A$	<b>g<sub>FS</sub></b>	-	15.5	-	<b>S</b>
Input Capacitance	$V_{DS}=25V$ $V_{GS}=0V$ $f=1.0MHz$	<b>C<sub>iss</sub></b>	-	2200	-	<b>pF</b>
Output Capacitance		<b>C<sub>oss</sub></b>	-	280	-	
Reverse Transfer Capacitance		<b>C<sub>rss</sub></b>	-	177	-	
Total Gate Charge	$V_{DS}=15V$ $I_D=24A$ $V_{GS}=10V$	<b>Q<sub>g</sub></b>	-	42	-	<b>nC</b>
Gate-Source Charge		<b>Q<sub>gs</sub></b>	-	4	-	
Gate-Drain("Miller") Charge		<b>Q<sub>gd</sub></b>	-	13	-	
Turn-on delay time	$V_{DS}=15V$ $I_D=15A$ $R_{GEN}=3.3\Omega$ $V_{GS}=10V$	<b>t<sub>d(on)</sub></b>	-	12.6	-	<b>ns</b>
Turn-on Rise Time		<b>T<sub>r</sub></b>	-	19.5	-	
Turn-Off Delay Time		<b>t<sub>d(OFF)</sub></b>	-	42.8	-	
Turn-Off Fall Time		<b>t<sub>f</sub></b>	-	13.2	-	
Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V, \text{ Force Current}$	<b>I<sub>S</sub></b>	-	-	100	<b>A</b>
Pulsed Source Current <sup>2,6</sup>		<b>I<sub>SM</sub></b>	-	-	400	<b>A</b>
Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=30A$	<b>V<sub>SD</sub></b>	-	-	1.2	<b>V</b>
Body Diode Reverse Recovery Time	$I_F=30A, di/dt=100A/\mu s$	<b>t<sub>rr</sub></b>	-	19	-	<b>ns</b>
Body Diode Reverse Recovery Charge		<b>Q<sub>rr</sub></b>	-	11	-	<b>nC</b>

Note :

- 1.The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L=0.1mH, I_{AS} = 45.8A$
- 4.The power dissipation is limited by 175°C junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.
- 6.Package limitation current is 85A

Ratings and Characteristic Curves

Typical Characteristics

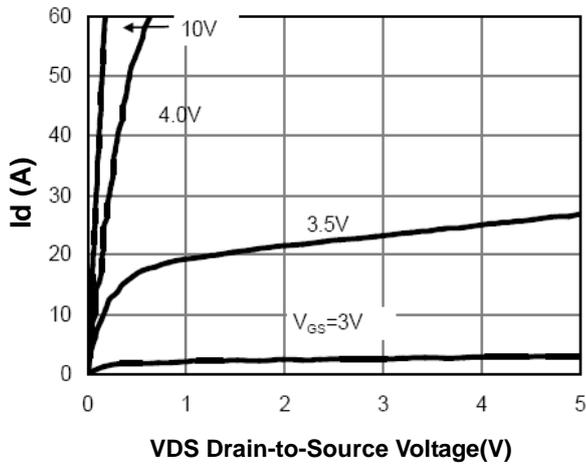


Figure 1. Output Characteristics

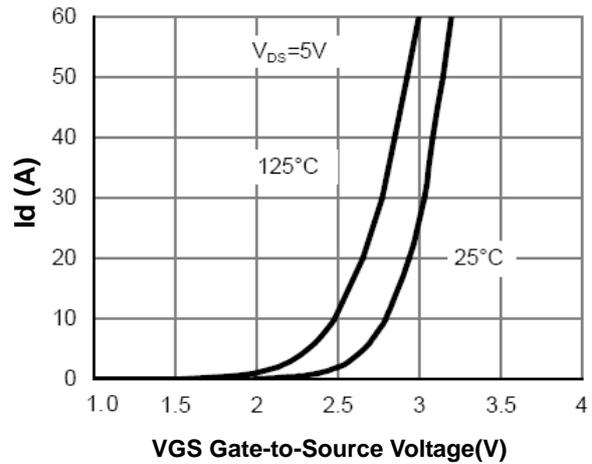


Figure 2. Transfer Characteristics

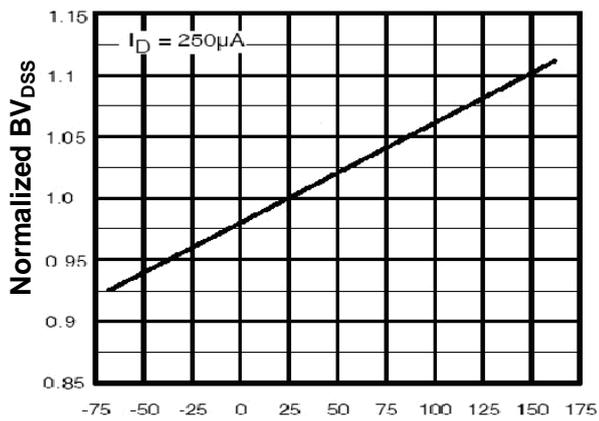


Figure 3. Max  $BV_{DSS}$  vs Junction Temperature

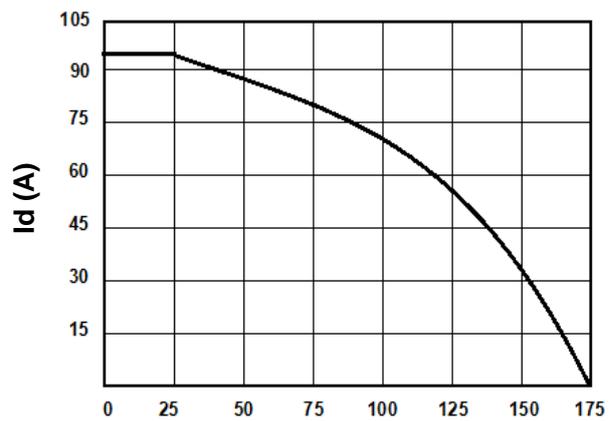


Figure 4. Drain Current

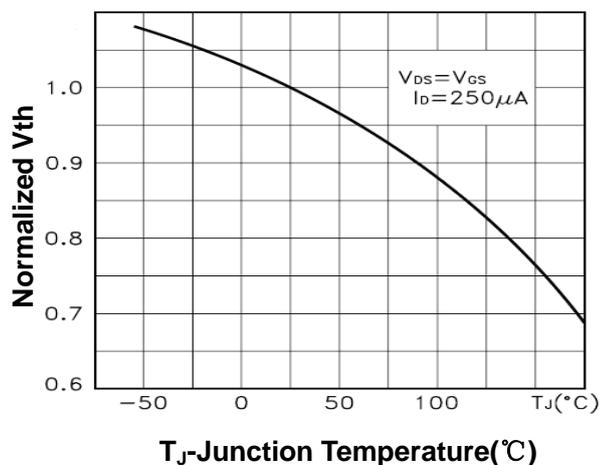


Figure 5.  $V_{GS(th)}$  vs Junction Temperature

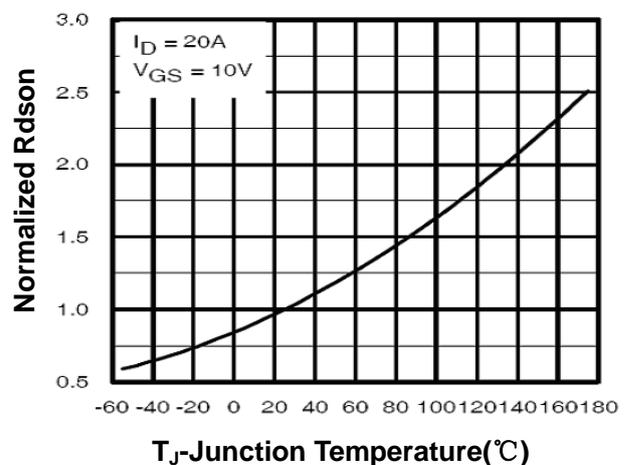


Figure 6.  $R_{DS(ON)}$  vs Junction Temperature

Ratings and Characteristic Curves

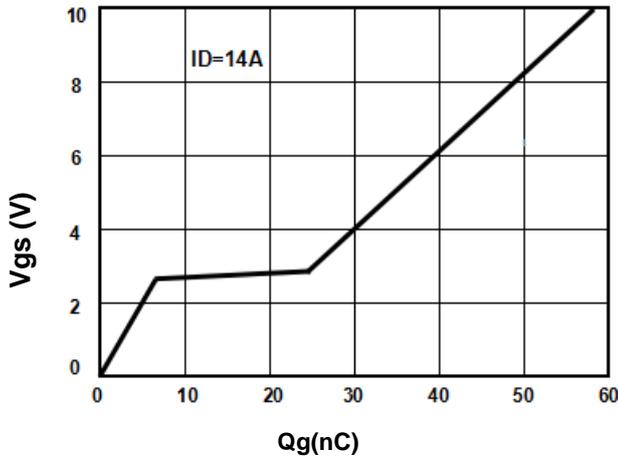


Figure 7. Gate Charge Waveforms

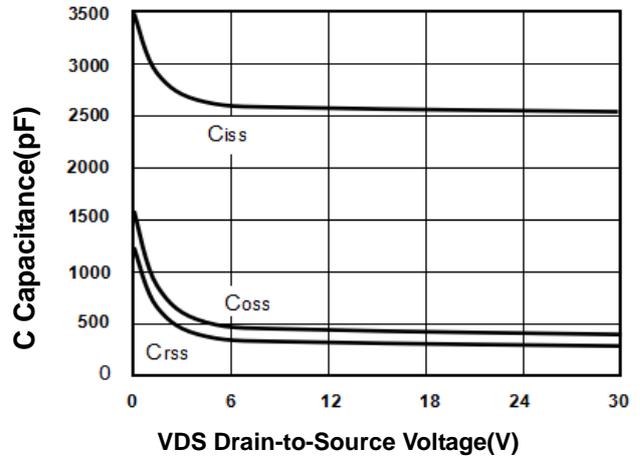


Figure 8. Capacitance

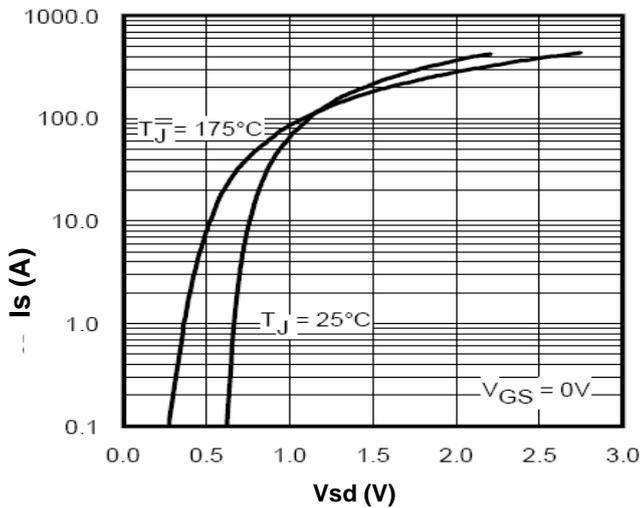


Figure 9. Body-Diode Characteristics

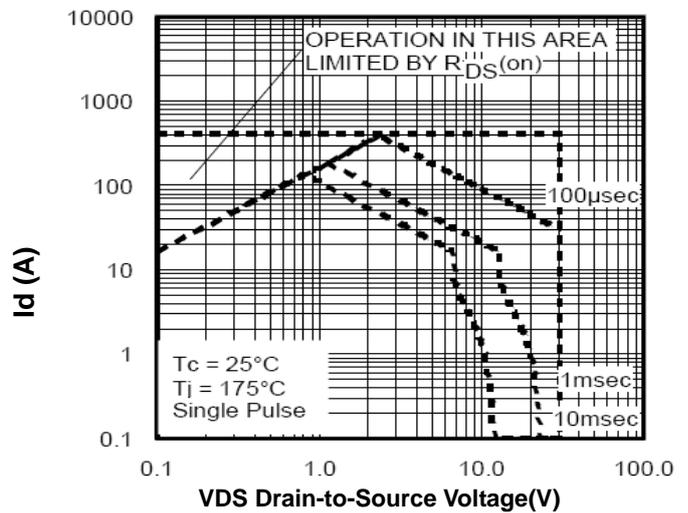


Figure 10. Maximum Safe Operating Area

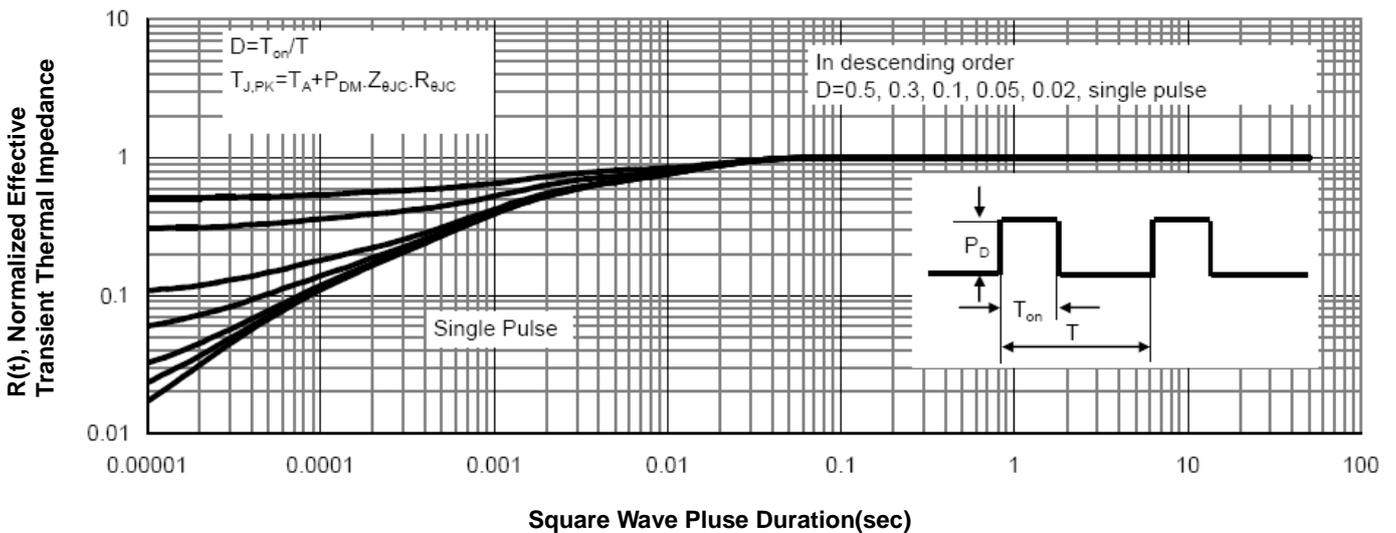
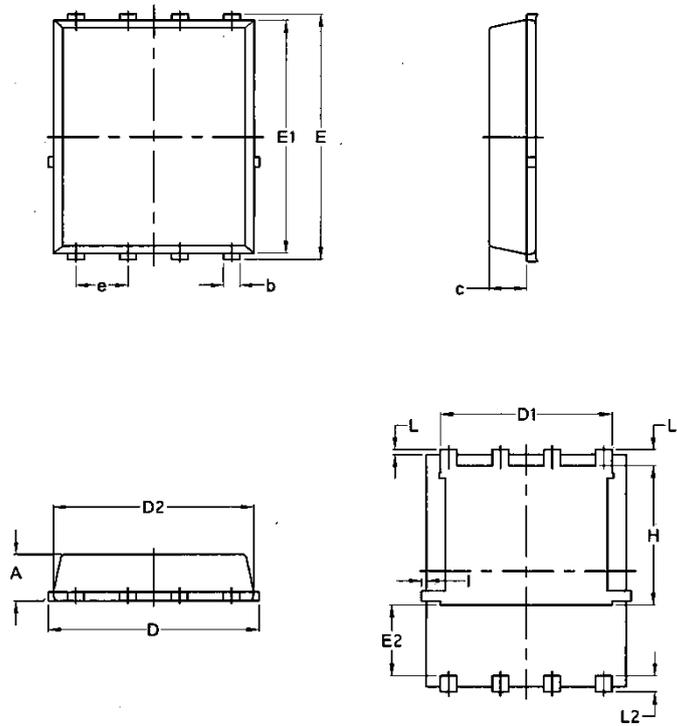


Figure 11. Normalized Maximum Transient Thermal Impedance

PDFN5\*6-8L



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070